

Form 1449 (Modified)			Atty Docket No. NSC1P296/P05887	Application No.: NEW 101826755
Information Disclosure Statement By Applicant			Applicant: Soon et al.	
(Use Several Sheets if Necessary)			Filing Date HEREWITH	4/15/04
			Group	2811
			UNASSIGNED	

U.S. Patent and Published Documents

Examiner Initial	No.	Patent No.	Date	Patentee	Class	Sub-class	Filing Date
QWQ	A1	5,328,079	07/12/1994	Mathew et al.			
	A2	5,408,127	4/18/95	Mostafazadeh			
	A3	4,818,895	4/4/89	Kaufman			
	A4	5,735,030	4/7/98	Orcutt			
	A5	6,399,421	06/02	Han et al.			
	A6	5,463,253	10/95	Waki et al.			
	A7	6,437,429	08/02	Wu et al.			
	A8	6,118,184	09/00	Ishio et al.			
	A9	5,471,369	11/95	Honda et al.			
	A10	2002/0137327	09/02	Arakawa			
QWQ	A11	5,545,922	08/96	Golwalker et al.			
QWQ	A12	6,353,265	03/02	Michii			

Foreign Patent or Published Foreign Patent Application

Examiner Initial	No.	Document No.	Publication Date	Country or Patent Office	Class	Sub-class	Translation Yes	Translation No
QWQ	B1	WO02/08257	10/17/02	WIPO				
QWQ	B2	EP0753891	1/15/97	EPO				

Other Documents

Examiner Initial	No.	Author, Title, Date, Place (e.g. Journal) of Publication
QWQ	C1	John Barber, "Plastic Packaging and the Effects of Surface Mount Soldering Techniques," Microchip Technology, Inc., 12 pages, 1995
QWQ	C2	Lai et al., Nordic Electronic Packaging Guideline, Chapter A, printed from: http://www.extra.ivf.se/mgl/A-WireBonding/ChapterA.htm , on March 16, 2004, 25 Pages
QWQ	C3	Prof. Daniel F. Baldwin, "Fundamentals of IC Assembly," McGraw-Hill, Chapter. 9, pages 342-353, 2001
QWQ	C4	Semiconductor Packaging Assembly Technology, printed from www.national.com , 8 pages, 1999

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<i>Rko</i>	C5	Nakanishi et al., "Development of High Density Memory IC Package by Stacking IC Chips," Abstract No. XP000624986, IEEE, Vol. Conf. 45, Pages 634-640 (1995)
<i>dko</i>	C6	Patent Abstract of Japan, Pub No. 63219131, Pub Date 9/12/88, 2 Pages
Examiner <i>Daryl K. Orr</i>	Date Considered	1/11/05

Examiner: Initial citation considered. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.